CLAIMS:

1. A receiving system for accommodating a substrate stack,

wherein the receiving system is configured such that the substrate stack is only fixed in a peripheral area of the substrate stack,

wherein the receiving system comprises:

mechanical clamps for clamping the sides of the substrate stack in the peripheral area of the substrate stack; and

an attaching unit for temporarily prefixing substrates of the substrate stack, wherein the attaching unit is configured to temporarily prefix the substrates of the substrate stack by a tacking method,

wherein the tacking is done with heat application; and

wherein laser radiation is used for the heat application.

2. A handling system for handling a substrate stack including the receiving system according to claim 1, wherein the handling system comprises a robot.

3. A device for aligning and bonding substrates, comprising at least an alignment unit, a bonding unit and a transfer section between the alignment unit and the bonding unit for transferring the substrates from the alignment unit to the bonding unit, wherein within the transfer section comprises the handling system according to claim 2 for transferring the substrates.

4. The device according to claim 3, wherein the transfer section comprises a vacuum transfer section.

5. The device according to claim 3 or 4, wherein at least the alignment unit, the bonding unit and the transfer section are configured as independently controllable modules.

6. A method for accommodating a substrate stack, the method comprising the steps of:

clamping the sides of the substrate stack only in a peripheral area of the substrate stack using mechanical clamps; and

temporarily prefixing substrates of the substrate stack using an attaching unit, wherein the prefixing comprises a tacking fixing method,

wherein the tacking is done with heat application; and

wherein laser radiation is used for the heat application.

7. A method for transferring a substrate stack, the method comprising the steps of:

clamping the sides of the substrate stack only in a peripheral area of the substrate stack using mechanical clamps; and

temporarily prefixing substrates of the substrate stack using an attaching unit, wherein the prefixing comprises a tacking fixing method;

wherein the tacking is done with heat application; and

wherein laser radiation is used for the heat application.

8. The method according to claim 7, wherein the substrate stack is transferred from an alignment unit to a bonding unit.